

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Original) A component built-in wiring board, comprising:

a conductive layer extending in a thickness direction of the board and buried in the board without being exposed from an upper and a lower surface of the board;

an electrical/electronic component having a terminal and buried in the board with the terminal facing the buried conductive layer;

a connecting member provided in a gap between the terminal of the buried electrical/electronic component and the conductive layer to electrically/mechanically connect the terminal and the conductive layer; and

two upper and lower insulating layers which cover an outer surface of the buried electrical/electronic component excluding a portion connected to the connecting member and which are in close contact with a top and a bottom in the board thickness direction of the electrical/electronic component.

2. (Original) The component built-in wiring board as set forth in claim 1, wherein the electrical/electronic component is one of a semiconductor chip, a semiconductor package, a chip capacitor, a chip resistor, and a chip inductor.

3. (Original) The component built-in wiring board as set forth in claim 1, further comprising wiring layers electrically connectable in a lateral direction to the conductive layer, the number of the wiring layers being four.

4. (Original) The component built-in wiring board as set forth in claim 3, wherein the wiring layers are electrically connected to one another via conductive bumps.

5. (Original) The component built-in wiring board as set forth in claim 4, wherein the conductive bumps sandwich the wiring layers to be laid one over another.

6. (Original) The component built-in wiring board as set forth in claim 1, further comprising:

two inner wiring layers provided to be in contact with inner surfaces of the two upper and lower insulating layers respectively; and

two outer wiring layers provided to be in contact with outer surfaces of the two upper and lower insulating layers respectively,

wherein the inner wiring layers and the outer wiring layers sandwiching the two upper and lower insulating layers respectively are electrically connected to each other via conductive bumps.

7. (Original) The component built-in wiring board as set forth in claim 1, wherein the connecting member is one of solder and conductive resin.

8. - 24. (Cancelled)